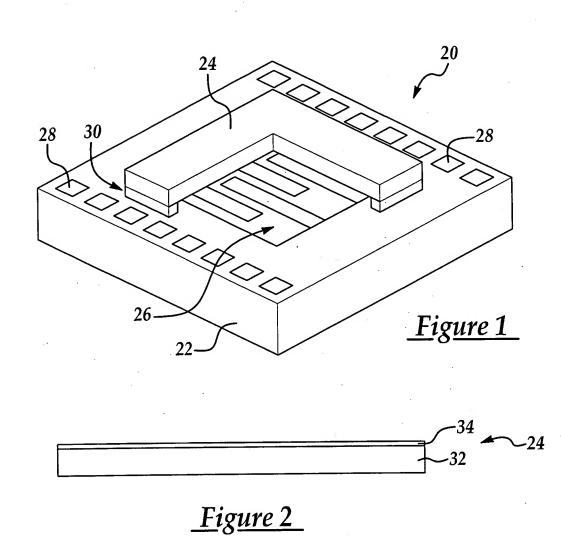
Inventor: Kuo-Lung

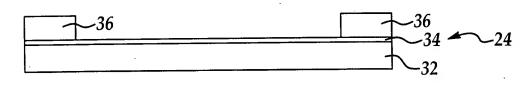
Serial No.: To Be Assigned Filed: Herewith

For: MEMS Micro-Cap Wafer Level Chip Scale Package

Attorney Doc. No.: 68,700-015

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<u>Figure 3</u>

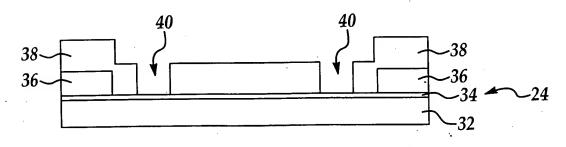


Figure 4

Inventor: Kuo-Lung

Serial No.: To Be Assigned Filed: Herewith
For: MEMS Micro-Cap Wafer Level Chip Scale Package

Attorney Doc. No.: 68,700-015

